

## Electronic Acknowledgement Receipt

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<b>Application Number:</b>	10551745
<b>International Application Number:</b>	
<b>Confirmation Number:</b>	5789
<b>Title of Invention:</b>	Method for the Multi-Stage Production of Diffusion Soldered Connections for Power Components Comprising Semiconductor Chips
<b>First Named Inventor/Applicant Name:</b>	Edmund Riedl
<b>Customer Number:</b>	25281
<b>Filer:</b>	Mark L. Gleason/Cindy Schlotz
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<b>Application Type:</b>	U.S. National Stage under 35 USC 371

### Payment information:

Submitted with Payment	no
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### File Listing:

Document Number	Document Description	File Name	File Size(Bytes) /Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed	SupplementalInformationDisclosureStatementuspto.pdf	33015 e37de4ffbdbb604d9899d375a6f64464050fc3821	no	4

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2	Foreign Reference	DE2930779uspto.pdf	1018698 400b382457be9cde1a2ff54f3d3ca1e0756bf58	no	25
<b>Warnings:</b>					
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3	Foreign Reference	JP54150076uptos.pdf	320736 b4f229b53bda39e2ffbca48122f112fd7ca92257	no	5
<b>Warnings:</b>					
<b>Information:</b>					
4	Foreign Reference	JP2000294444upsto.pdf	447282 6819cab61458374ad954accb5a8993fc003a558d	no	5
<b>Warnings:</b>					
<b>Information:</b>					
5	Foreign Reference	JP05237694uptos.pdf	54729 d9b3269e1b2c50635f20304a01e1db496825d524	no	1
<b>Warnings:</b>					
<b>Information:</b>					
6	Foreign Reference	JP2001077049uspto.pdf	1221295 be0bbf3ba189a3daa0f620274fbfb57d523765db	no	10
<b>Warnings:</b>					
<b>Information:</b>					
7	Foreign Reference	WO200021346upsto.pdf	85150 2ca75534e76e0675c5f52b285d8487ef27927684	no	1
<b>Warnings:</b>					
<b>Information:</b>					
8	NPL Documents	XPuspto.pdf	56828 13830cf3e98d88f88bdb9779d2e4cc54d44eb466	no	1
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If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

**National Stage of an International Application under 35 U.S.C. 371**

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

**New International Application Filed with the USPTO as a Receiving Office**

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.